# DISCRETE SEMICONDUCTORS

# DATA SHEET



# **BAX12**Controlled avalanche diode

Product specification Supersedes data of April 1996 1996 Sep 17





**BAX12** 

#### **FEATURES**

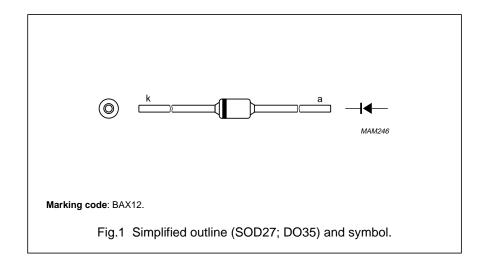
- Hermetically sealed leaded glass SOD27 (DO-35) package
- Switching speed: max. 50 ns
- · General application
- Continuous reverse voltage: max. 90 V
- Repetitive peak reverse voltage: max. 90 V
- Repetitive peak forward current: max. 800 mA
- Repetitive peak reverse current: max. 600 mA
- Capable of absorbing transients repetitively.

#### **APPLICATIONS**

 Switching of inductive loads in semi-electronic telephone exchanges.

#### DESCRIPTION

The BAX12 is a controlled avalanche diode fabricated in planar technology, and encapsulated in the hermetically sealed leaded glass SOD27 (DO-35) package.



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage	note 1	_	90	V
V <sub>R</sub>	continuous reverse voltage	note 1	_	90	V
IF	continuous forward current	see Fig.2; note 2	_	400	mA
I <sub>FRM</sub>	repetitive peak forward current		_	800	mA
I <sub>FSM</sub>	non-repetitive peak forward current	square wave; T <sub>j</sub> = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	55	Α
		t = 100 μs	_	15	Α
		t = 10 ms	_	9	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C; note 2	_	450	mW
I <sub>RRM</sub>	repetitive peak reverse current		_	600	mA
E <sub>RRM</sub>	repetitive peak reverse energy	$t_p \ge 50 \ \mu s; \ f \le 20 \ Hz; \ T_j = 25 \ ^{\circ}C$	_	5.0	mJ
T <sub>stg</sub>	storage temperature		-65	+200	°C
Tj	junction temperature		_	200	°C

#### Notes

- 1. It is allowed to exceed this value; see Figs 8 and 9. Care should be taken not to exceed the I<sub>RRM</sub> rating.
- 2. Device mounted on an FR4 printed circuit-board; lead length 10 mm.

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# **ELECTRICAL CHARACTERISTICS**

 $T_j = 25$  °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.3			
		$I_F = 10 \text{ mA}$	_	750	mV
		$I_F = 50 \text{ mA}$	_	840	mV
		I <sub>F</sub> = 100 mA	_	900	mV
		$I_F = 200 \text{ mA}$	_	1.0	V
		$I_F = 400 \text{ mA}$	_	1.25	V
I <sub>R</sub>	reverse current	see Fig.5			
		V <sub>R</sub> = 90 V	_	100	nA
		$V_R = 90 \text{ V}; T_j = 150 ^{\circ}\text{C}$	_	100	μΑ
V <sub>(BR)R</sub>	reverse avalanche breakdown voltage	I <sub>R</sub> = 1 mA	120	170	V
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 0; see Fig.6	_	35	pF
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 30$ mA to $I_R = 30$ mA; $R_L = 100$ $\Omega$ ; measured at $I_R = 3$ mA; see Fig.10	_	50	ns

# THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	lead length 10 mm; note 1	375	K/W

# Note

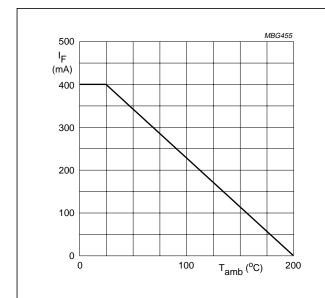
1. Device mounted on a printed circuit-board without metallization pad.

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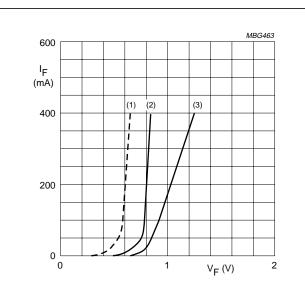
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## **GRAPHICAL DATA**



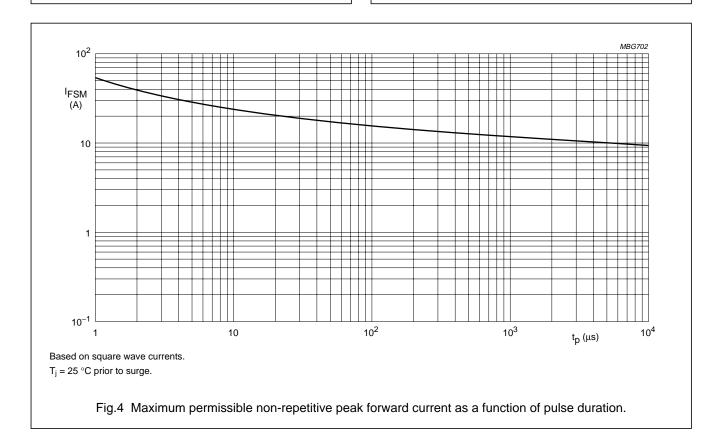
Device mounted on an FR4 printed-circuit board; lead length 10 mm.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.

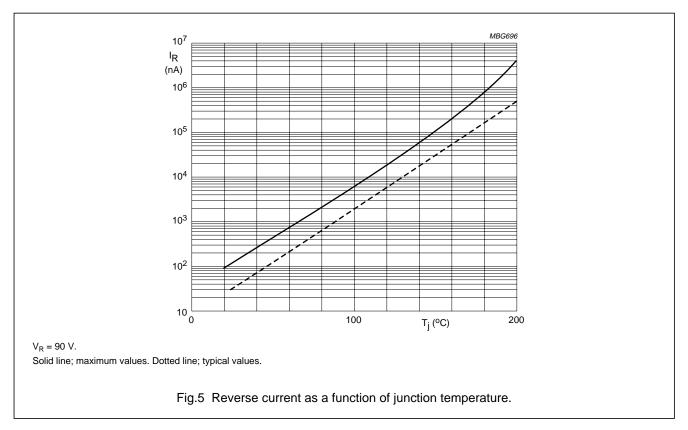


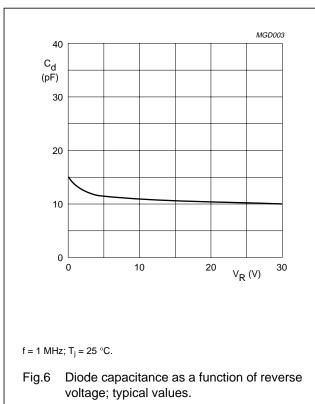
- (1)  $T_j = 175$  °C; typical values.
- (2)  $T_j = 25$  °C; typical values.
- (3)  $T_j = 25$  °C; maximum values.

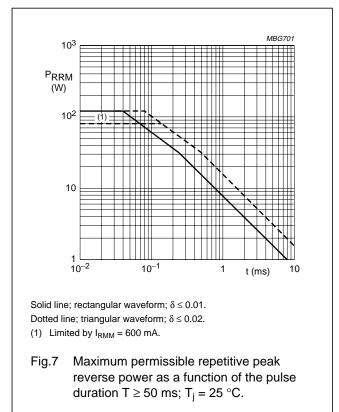
Fig.3 Forward current as a function of forward voltage.



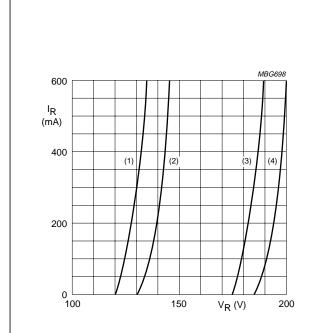
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Reverse voltages higher than the  $\ensuremath{V_R}$  ratings are allowed, provided:

- a. The transient energy  $\leq$  7.5 mJ at P<sub>RRM</sub>  $\leq$ 30 W; T<sub>j</sub> = 25 °C; the transient energy  $\leq$  5 mJ at P<sub>RRM</sub> = 120 W; T<sub>j</sub> = 25 °C (see Fig.7).
- b. T  $\geq$  50 ms;  $\delta$   $\leq\!0.01$  (rectangular waveform) (see Fig.9).
  - $\delta~\leq\!\!0.02$  (triangular waveform) (see Fig.9).

With increasing temperature, the maximum permissible transient energy must be decreased by 0.03 mJ/K.

- (1)  $T_j = 25$  °C; minimum values.
- (2)  $T_j = 175$  °C; minimum values.
- (3)  $T_j = 25$  °C; maximum values.
- (4)  $T_j = 175$  °C; maximum values.

Fig.8 Reverse current as a function of continuous reverse voltage.

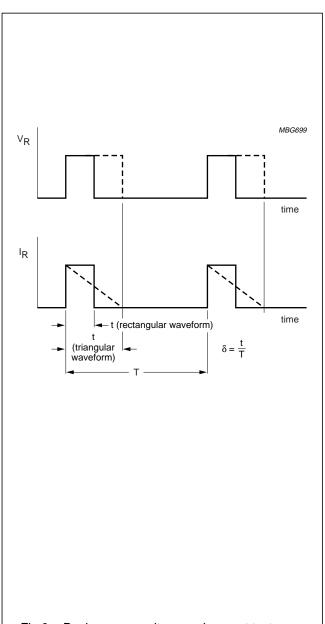
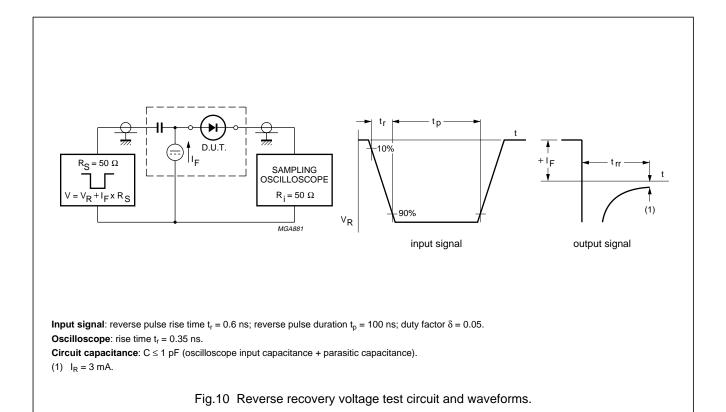


Fig.9 Peak reverse voltage and current test pulses.

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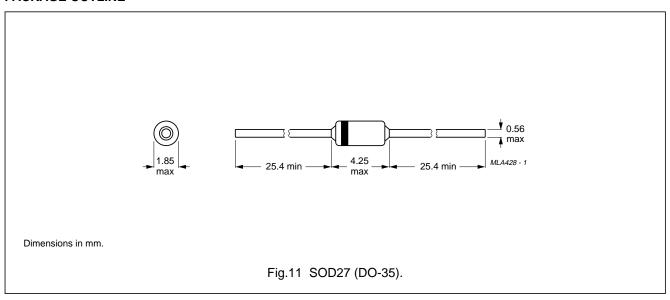


Product specification Philips Semiconductors

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#### **PACKAGE OUTLINE**



#### **DEFINITIONS**

Data Sheet Status			
Objective specification	This data sheet contains target or goal specifications for product development.		
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.		
Product specification	This data sheet contains final product specifications.		
Limiting values			

#### Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

## **Application information**

Where application information is given, it is advisory and does not form part of the specification.

# LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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